

**Search Notes****Application No.**

10/685,485

**Examiner**

Stephen W. Smoot

**Applicant(s)**

FANG, JEN KUANG

**Art Unit**

2813

**SEARCHED**

Class	Subclass	Date	Examiner
438	108	5/14/2004	SWS
438	122	5/14/2004	SWS
438	124	5/14/2004	SWS
438	127	5/14/2004	SWS
438	612	5/14/2004	SWS
438	613	5/14/2004	SWS
438	615	5/14/2004	SWS
Updated	Above	11/3/2004	SWS

**INTERFERENCE SEARCHED**

Class	Subclass	Date	Examiner

**SEARCH NOTES  
(INCLUDING SEARCH STRATEGY)**

	DATE	EXMR
Considered all citations from parent application. <i>S.W.S.</i>	5/14/2004	<i>S.W.S.</i> SWS
Key Words: Flip Chip; Heat Sink; Solder Bump - Reflow; Contact Pad - UBM, Underbump Metallurgy. <i>S.W.S.</i>	5/14/2004	<i>S.W.S.</i> SWS
Updated Above Search <i>S.W.S.</i>	11/3/2004	<i>S.W.S.</i> SWS
Search Tools - EAST (attached); USPAT; US PG PUBS; Derwent; EPO; JPO; IBM TDB <i>11-3-04</i>	5/14/2004 <i>11-3-04</i>	<i>S.W.S.</i> SWS